

A. Amendments to the Claims

1. (Canceled)
2. (New) A solid state keyboard formed by:
 - (a) depositing a layer of decorative material onto at least a portion of a substrate;
 - (b) depositing a first layer of conductive material as a thin film onto at least a portion of the structure resulting from step (a), said first layer of conductive material being arranged in the form of a first sensing electrode having a shape amenable to substantial coverage by a predetermined object;
 - (c) depositing a second layer of conductive material onto at least a portion of the structure resulting from step (b), at least a portion of said second layer of conductive material being electrically coupled to at least a portion of said first layer of conductive material, said second layer of conductive material being arranged in the form of a first electrical trace and a first bonding pad; and
 - (d) electrically coupling a first electrical component to said first bonding pad.
3. (New) The solid state keyboard of claim 2, said second layer of conductive material further being arranged in the form of a second sensing electrode having a shape amenable to substantial coverage by a predetermined object.

4. (New) The solid state keyboard of claim 2 further formed by depositing a first layer of dielectric material onto at least a portion of the structure resulting from step (c), said first layer of dielectric material being arranged in a form that enables electrically coupling said first electrical component to said first bonding pad.

5. (New) The solid state keyboard of claim 2 wherein said decorative material comprises an organic material.

6. (New) The solid state keyboard of claim 5 wherein said organic material comprises an epoxy.

7. (New) The solid state keyboard of claim 5 wherein said organic material is ultraviolet curable.

8. (New) The solid state keyboard of claim 2 wherein said first layer of conductive material is substantially transparent.

9. (New) The solid state keyboard of claim 2 wherein said step of electrically coupling comprises soldering.

10. (New) The solid state keyboard of claim 4, said second layer of conductive material further being arranged in the form of a second bonding pad and said keyboard further

formed by depositing a third layer of conductive material onto at least a portion of said first layer of dielectric material.

11. (New) The solid state keyboard of claim 10, at least a portion of said third layer of conductive material being electrically coupled to said second bonding pad.

12. (New) The solid state keyboard of claim 11 further formed by depositing a second layer of dielectric material onto at least a portion of said third layer of conductive material.

13. (New) A solid state keyboard formed by:

(a) depositing at least one layer of decorative material onto a substrate;
(b) depositing a first conductive material as a thin film onto the structure resulting from step (a), said first conductive material being arranged in the form of a sensing electrode having a shape amenable to substantial coverage by a predetermined object, an electrical trace, and a bonding pad; and
(c) electrically coupling an electrical component to said bonding pad.

14. (New) The solid state keyboard of claim 13 further formed by depositing a dielectric mask on a portion of the structure resulting from step (b), said mask being arranged in a form that enables electrically coupling said electrical component to said bonding pad.

15. (New) The solid state keyboard of claim 13 wherein said decorative material comprises an organic material.

16. (New) The solid state keyboard of claim 15 wherein said organic material comprises an epoxy.

17. (New) The solid state keyboard of claim 13 wherein said step of electrically coupling comprises soldering.

18. (New) A solid state keyboard comprising:
a substrate;
at least one layer of decorative material disposed on said substrate;
a first conductive material disposed as a thin film on at least a portion of said decorative material, said first conductive material arranged in the form of a sensing electrode having a shape amenable to substantial coverage by a predetermined object, an electrical trace and a bonding pad; and
an electrical component electrically coupled to said bonding pad.

19. (New) The solid state keyboard of claim 18 wherein said decorative material comprises an organic material.

20. (New) The solid state keyboard of claim 19 wherein said organic material comprises an epoxy.

21. (New) The solid state keyboard of claim 18 wherein said electrical component is soldered to said bonding pad.

22. (New) The solid state keyboard of claim 18 further comprising a mask disposed on a portion of said first conductive material, said mask being arranged in a form that enables electrically coupling said electrical component to said bonding pad.

23. (New) A solid state keyboard comprising:

a substrate;

at least one layer of decorative material disposed on said substrate;

a thin film of a first conductive material disposed on said decorative material, said thin film of a first conductive material being arranged in the form of a first sensing electrode having a shape amenable to substantial coverage by a predetermined object;

a layer of a second conductive material disposed on at least a portion of said thin film of a first conductive material, said layer of a second conductive material arranged in the form of a second sensing electrode having a shape amenable to substantial coverage by a predetermined object, an electrical trace, and a bonding pad; and

an electrical component coupled to said bonding pad.

24. (New) The solid state keyboard of claim 23 wherein said decorative material comprises an organic material.

25. (New) The solid state keyboard of claim 24 wherein said organic material comprises an epoxy.

26. (New) The solid state keyboard of claim 23 wherein said thin film of a first conductive material is substantially transparent.

27. (New) The solid state keyboard of claim 23 wherein said electrical component is soldered to said bonding pad.

28. (New) The solid state keyboard of claim 23 further comprising a mask disposed on at least a portion of said thin film of a first conductive material and at least a portion of said layer of a second conductive material, said mask being arranged in a form that enables electrically coupling said electrical component to said bonding pad.